

Model ID

# PSX307A

For substrate  
&  
wafer level PKG

Model No. NM-EFP3A

- Surface cleaning and modification of wafers and substrates improve bondability of metal and adhesion of resin.
- Increasing process number of wafers and substrates in the same time by enlarging vacuum chamber capacity improves productivity.
- Panasonic original plasma monitoring system suppresses abnormal discharge and newly introduced traceability function ensures process quality
- Flexible machine concept adapts versatile production model and supports process operation.
- Capability of  $\Phi 300$  mm wafer (with/without : dicing ring) contributes to wafer level package manufacturing.



\*It may not conform to Machinery Directive and EMC Directive in case of optional configuration and custom-made specification.

Model ID	PSX307A
Model No.	NM-EFP3A
Cleaning Method	Parallel plate RF back-sputtering method
Gas for Electrical Discharge *1	Ar [Option : O <sub>2</sub> , O <sub>2</sub> + He]
Power source	1-phase AC 200 / 208 / 220 / 230 / 240 $\pm 10$ V , 50 / 60 Hz , 6.00 kVA
Pneumatic source	0.49 MPa , 50 L / min [A.N.R.]
Dimension *2	W 900 mm $\times$ D 1 150 mm $\times$ H 1 650 mm
Mass *3	630 kg

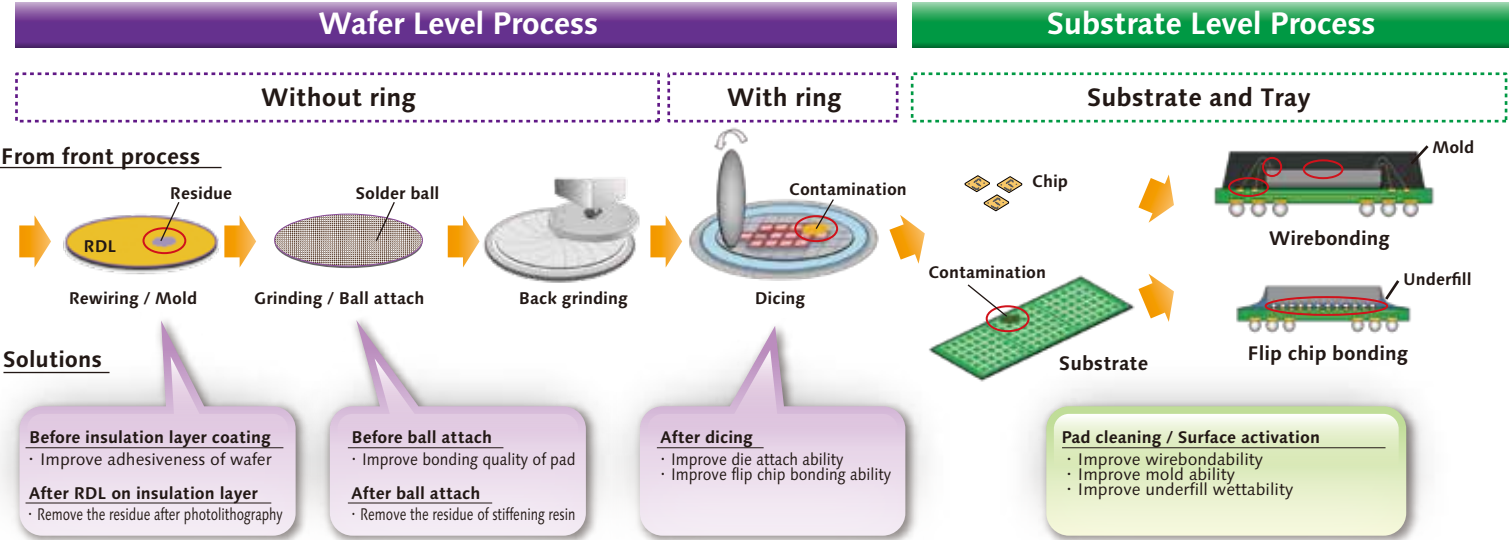
Specification (Target work) *4	Substrate	Wafer with dicing ring	Wafer without dicing ring
Work Size *5	L 50 mm $\times$ W 30 mm *6 to L 350 mm $\times$ W 350 mm	$\Phi 300$ mm *7	$\Phi 300$ mm

※Please refer to the specifications on details  
※Pre-confirmation by customer's works is required.

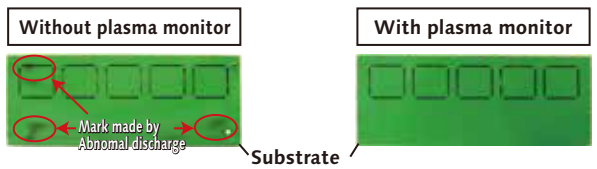
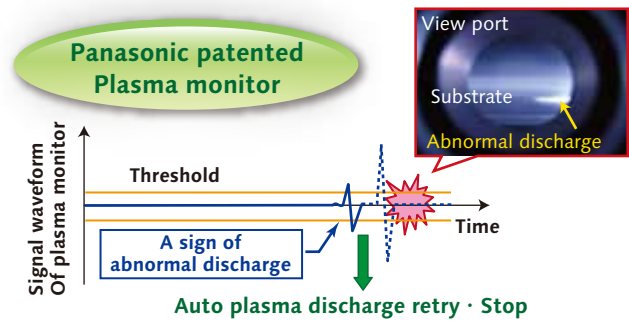
\*1 : If the optional oxygen gas is selected as electric discharge gas , nitrogen gas is also required to dilute exhaust  
\*2 : Excluding touch panel, emergency stop switch and signal tower.  
\*3 : In case of full option

\*4 : Please select a specification among three  
\*5 : Please consult us about the substrate thickness  
\*6 : Please contact us for the substrate with depth < 30 mm  
\*7 : outer diameter of ring :  $\square 380$  mm

**Achieve high quality production by plasma cleaning and modification from wafer level to substrate level assembly process**

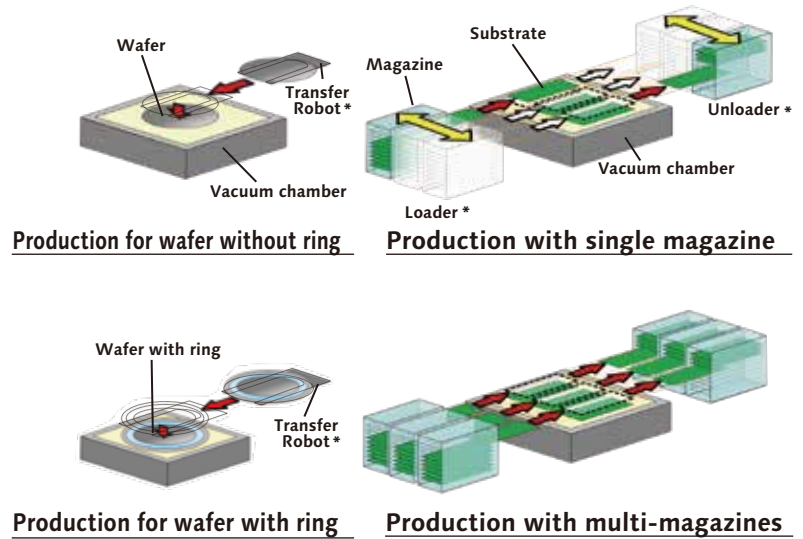


**High quality management with plasma monitor**



- Avoid substrate damage by abnormal discharge and prevent defect substrate passing to next process
- Record the log data of monitor for each substrates (Option)

**Flexibility for various type of production**



\* Transfer robot, loader/unloader are prepared by customer.

**⚠ Safety Cautions**

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

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